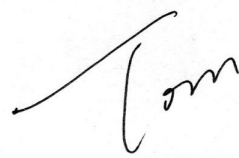
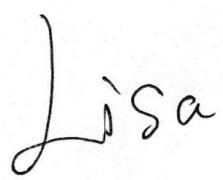




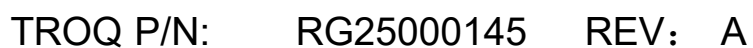
TROQ Electronic Co.,Ltd.
CRYSTAL UNIT SPECIFICATIONS

Customer	
Production Name	SMD CRYSTAL GLASS 5.0*3.2 2PIN
Customer P/N	N/A
TROQ P/N	RG25000145
Revision	A
Print Date	2026/8/26

Drawn	Checked	Approved
		



RoHS Compliant



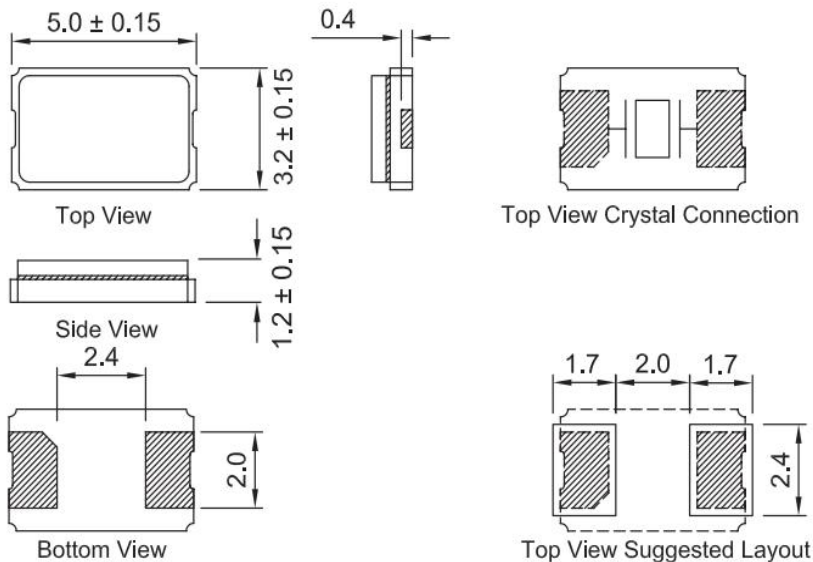
修订记录表

[illegible]

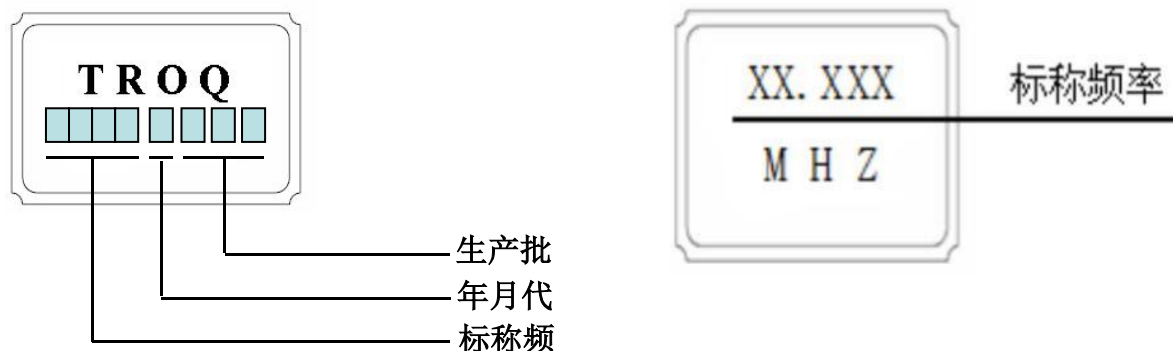
● ELECTRICAL PARAMETERS

谐振器产品技术指标	Min	Max	Units
1.Holder Type(型号规格)	GLASS 5.0*3.2 2PIN		
2.Mode of Oscillation (振动模式)	Fundamental		
3.Frequency (标称频率)	25.000000		MHz
4.Load Capacitance (CL) (负载电容)	18		pF
5.Shunt Capacitance (Co) (静态电容)	1	7	pF
6.Equivalent Resistance (谐振电阻)		40	Ω
7.Frequency Tolerance at 25℃ (调整频差)	-30	30	ppm
8.Stability over operation temperance (温度频差)	± 30		ppm
9.Insulation Resistance (at DC 100V) (绝缘电阻)	500		M Ω
10.Drive Level (激励功率)	100		uw
11.Operating Temperature Range (工作温度范围)	-20	70	℃
12. Storage Temperature Range (储存温度范围)	-40	85	℃
13. Aging (老化率)	± 5		ppm/year
14.Other(其它)	MSL (零件湿敏等级) Level 1		

OUTLINE DIMENSIONS(UNIT:mm) 外形尺寸 (单位: mm)



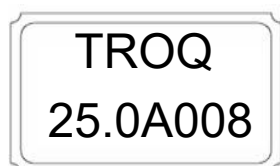
● Marking (标记)



● 年月代码

2024月份	1	2	3	4	5	6	7	8	9	10	11	12
2024年月码	A	B	C	D	E	F	G	H	J	K	L	M
2025月份	1	2	3	4	5	6	7	8	9	10	11	12
2025年月码	N	P	Q	R	S	T	U	V	W	X	Y	Z
2026月份	1	2	3	4	5	6	7	8	9	10	11	12
2026年月码	a	b	c	d	e	f	g	h	j	k	l	m
2027月份	1	2	3	4	5	6	7	8	9	10	11	12
2027年月码	n	p	q	r	s	t	u	v	w	x	y	z

注: 以上年月代码每四年一个循环。



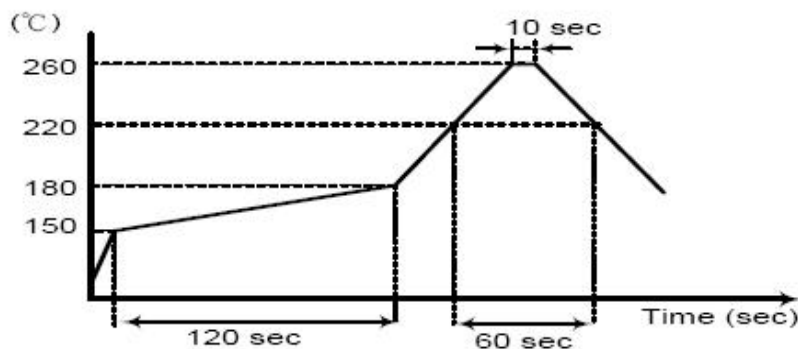
——→ 说明: 标称频率 25.000MHZ
2020年1月份制造, 生产批号为008
上述产品标志从2012年7月1日正式执行

● SUGGESTED REFLOW PROFILE (回流焊曲线图)

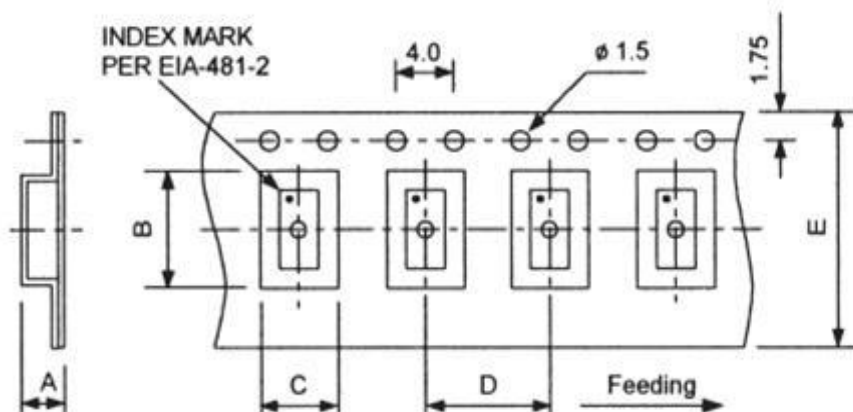
Total time:200sec.Max. (总时间: 200秒 最大)

Solder melting point:220℃ (熔点220 ℃)

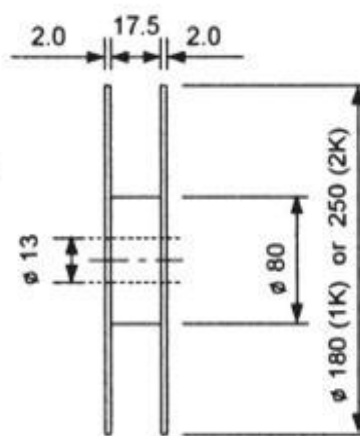
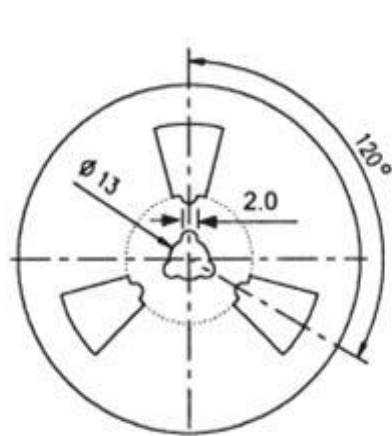
Profiles Feature (特性)		Pb-Free Assembly
Average Ramp-up Rate(Ts max to Tp)	平均升温速度	3℃/second Max
Preheat	预热	
■ Temperature Min (Ts min)	最低温度	125℃
■ Temperature Max (Ts max)	最高温度	200℃
■ Time (ts min to ts max)	从最低到最高时间	(60~180) seconds
Time maintained above	维持上述时间	
■ Temperature(T1)	温度	217℃
■ Time(tp)	时间	(60~150) seconds
Peak/Classification Temperature(Tp)	最高点温度	260 ℃
Time within 5℃ of actual Peak Temperature(tp)	高温维持时间	(20~40) seconds
Ramp-down rate	降温速度	6℃/second max
Time 25℃ to Peak Temperature	从25℃到最高温度的时间	8 minutes max
Suggest reflow times	建议 reflow次数	3 Times max



● PACKING (包装) 1Kpcs/REEL



SIZE	
A	1.7
B	5.45
C	3.65
D	8.0
E	12.0
IK	



REMARK :

1. 230 mm (9.05) minimum leader which consist of carrier and/or cover tape followed by a minimum of 160 mm (6.3) of empty carrier tape sealed with cover tape.
2. 160 mm (6.3) minimum trailer of empty carrier tape sealed with cover tape.

● RELIABILITY SPECIFICATIONS (信赖度试验)

No	Test Item (测试项目)	Test Conditions (测试条件)	Reference (参考)
1	High Temperature High Humidity Storage (高温、高湿、储存)	Temperature: 85°C±3°C 温度: 85°C±3°C Relative Humidity: 85%RH 相对湿度: 85%RH Time: 96 Hours 时间: 96小时	JIS C5023
2	High Temperature Storage (高温储存)	Temperature: 125°C±3°C 温度: 125°C±3°C Time: 96 Hours 时间: 96小时	MIL-STD-883E Method 1005.8
3	Low Temperature Storage (低温储存)	Temperature: -40°C±3°C 温度: -40°C±3°C Time: 96 Hours 时间: 96小时	MIL-STD-883E Method 1013
4	Thermal Shock (温度冲击)	Temperature 1: -55°C±5°C 温度 1: -55°C±5°C Temperature 2: 85°C±5°C 温度 2: 85°C±5°C Temperature change between T1 and T2 5 min T1和T2温度在5分钟内改变 10 cycles maintain T1 and T2 for 30 minutes each more cycle 每次循环30分钟共10次	MIL-STD-202F Method 107 Condition A
5	RESISTANCE TO SOLDER HEAT (耐焊接热)	Solder Temperature: 260°C±5°C 焊槽温度: 260°C±5°C Time: 10±1 Seconds 时间: 10±1秒	MIL-STD-202F Method 210E
6	Solderability (可焊性)	The solder pot temperature is 245±5°C, dwell time 5±0.5sec 245±5°C 焊锡槽浸润 5±0.5秒	J-STD-002B
7	Drop Test (落下试验)	3 Times Free Fall from 50cm height table to 3cm thickness hard wood board 从50cm高度3次跌落到3cm厚硬质木板上	JIS C6701
8	MECHANICAL SHOCK (机械冲击)	Half sine wave, 1000 G 半正弦波, 加速度 1000G 3 Times for all 3 directions X、Y、Z 三个相互垂直方向各三次	MIL-STD-202F Method 213B
9	Vibration (机械振动)	Frequency Range: 10Hz~55Hz 频率范围: 10Hz~55Hz Amplitude: 0.75mm 振幅: 0.75mm 2 Hours in each direction, total 6 Hours X、Y、Z 三个相互垂直方向各振动2小时	MIL-STD-883E Method 2007.3
10	Leakage Test (气密性)	Take measurements with a helium Leakage detector 氦质检漏 Leakage Rate ≤ 1×10 ⁻³ Pa cm ³ /s 漏率 ≤ 1×10 ⁻³ Pa cm ³ /s	MIL-STD-883E